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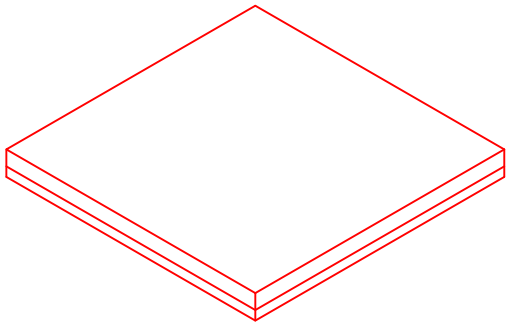
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C06100	05/06/99	E.B.	M.C.N.



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6 PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 100.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.

2. THE BASIC SOLDER BUMP GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL: X.X ±0.10, X.XX ±0.05, X.XXX ±0.03
ANGULAR: ±1°

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS	DATE
DRAWN: M. NOBLES	04/14/99
CHECKED: J. MICKSCH	04/29/99
ENG'R: H. BUENAOBRA	04/14/99
RELEASED: G. SCHULTZ	05/06/99

ANAM Industrial Co., LTD. Sungdong-Ku, Seoul, Korea
AMKOR Electronics, Inc. Chandler, Arizona, USA

amkor anam

TITLE: PACKAGE OUTLINE – CTBGA 100, 11.00mm X 11.00mm, 2 LAYER, 1.00mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	75440	00

STRIP DWG NUMBER/REV	CUST CODE	SCALE: 8:1	SHEET 1 OF 3
N/A	N/A		